

FIG. 1A

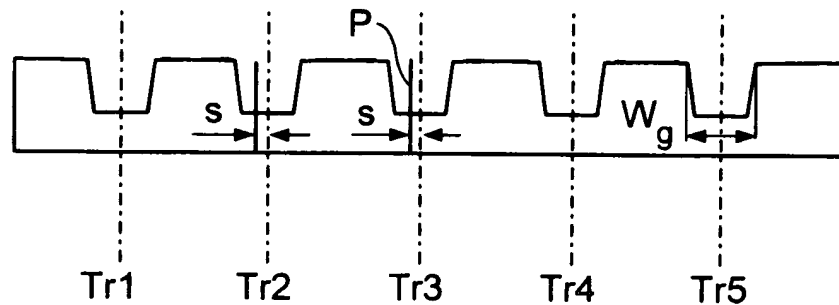


FIG. 1B

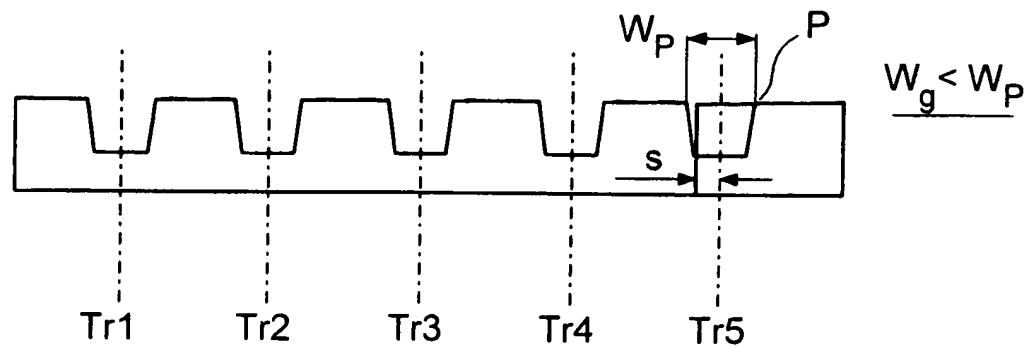


FIG. 1C

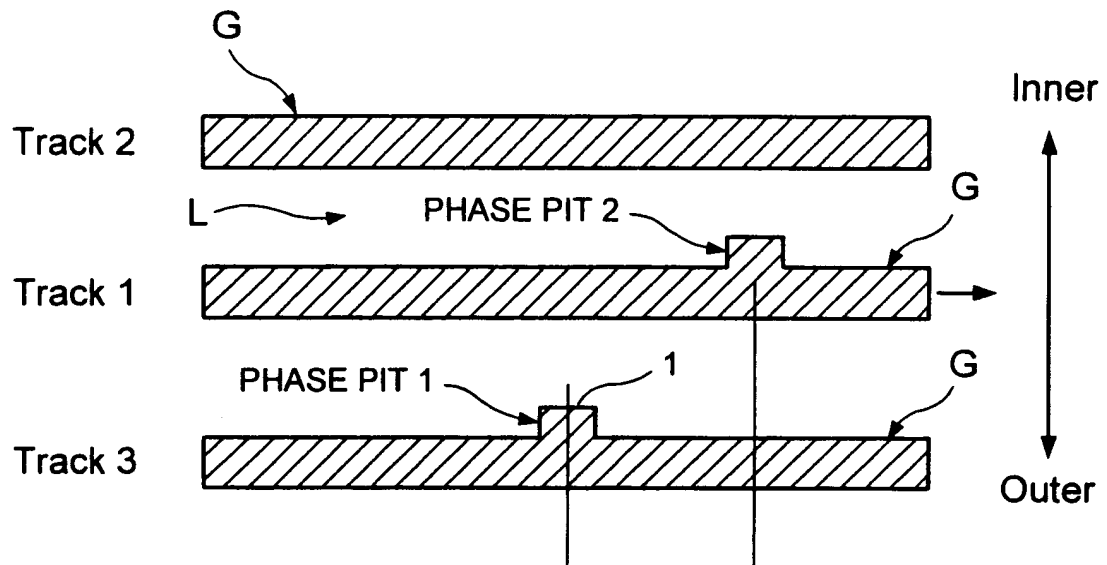


FIG. 2A

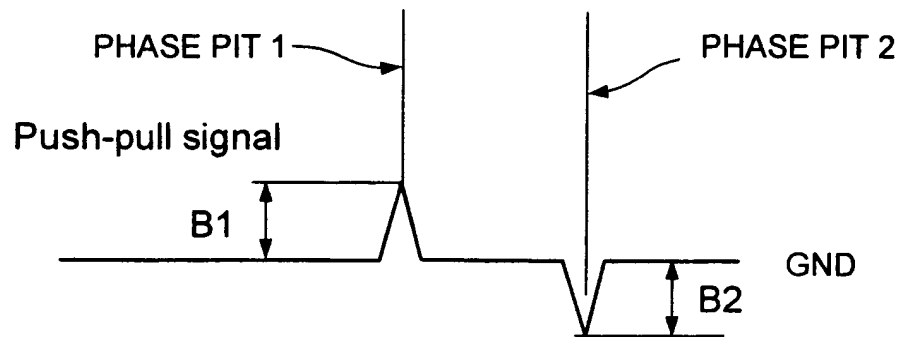


FIG. 2B

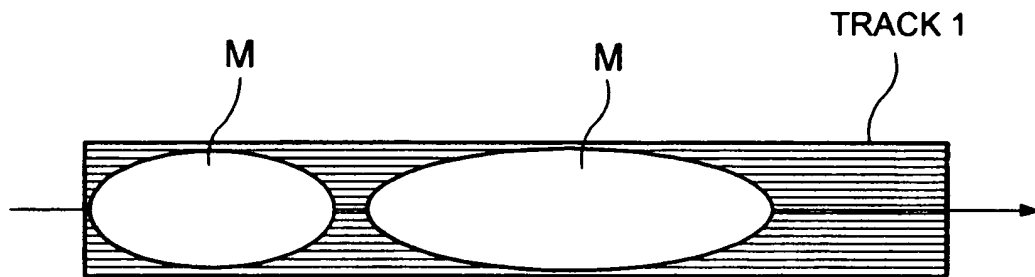


FIG. 3A

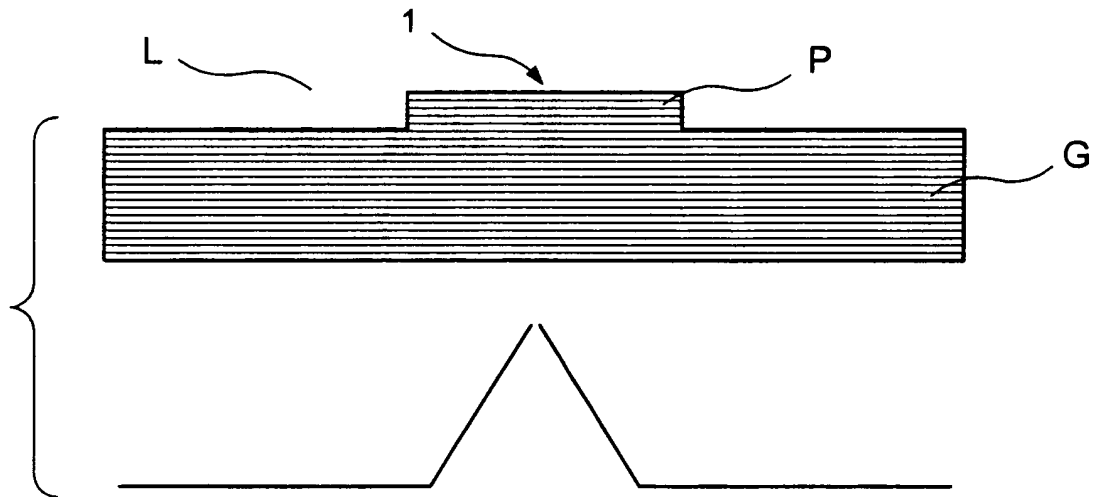


FIG. 3B

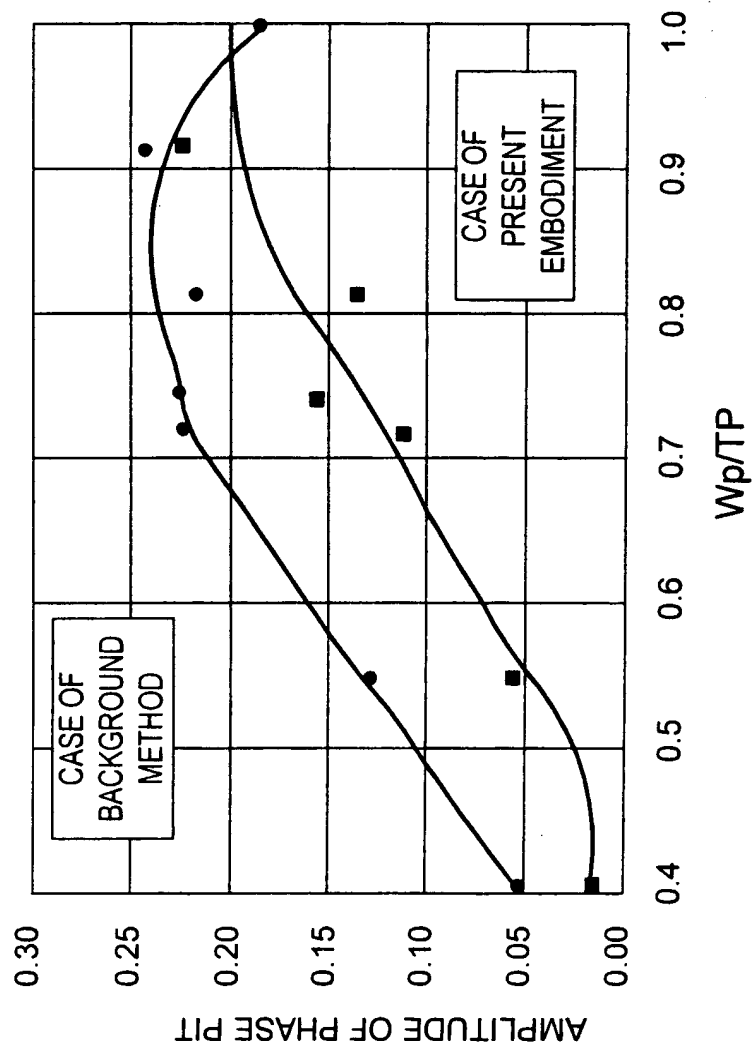
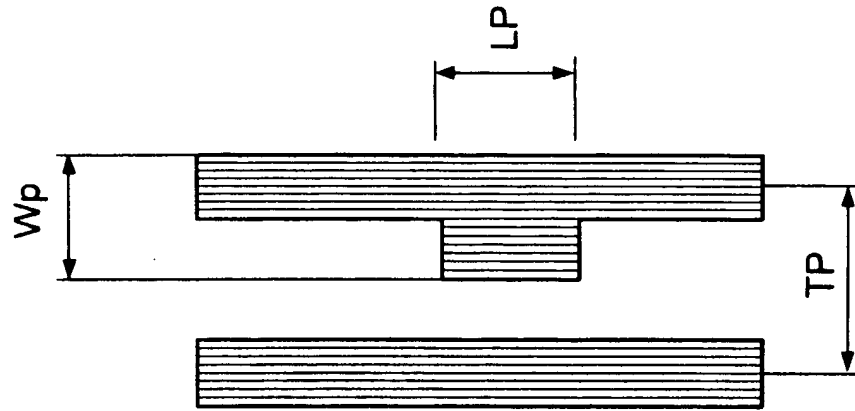


FIG. 4

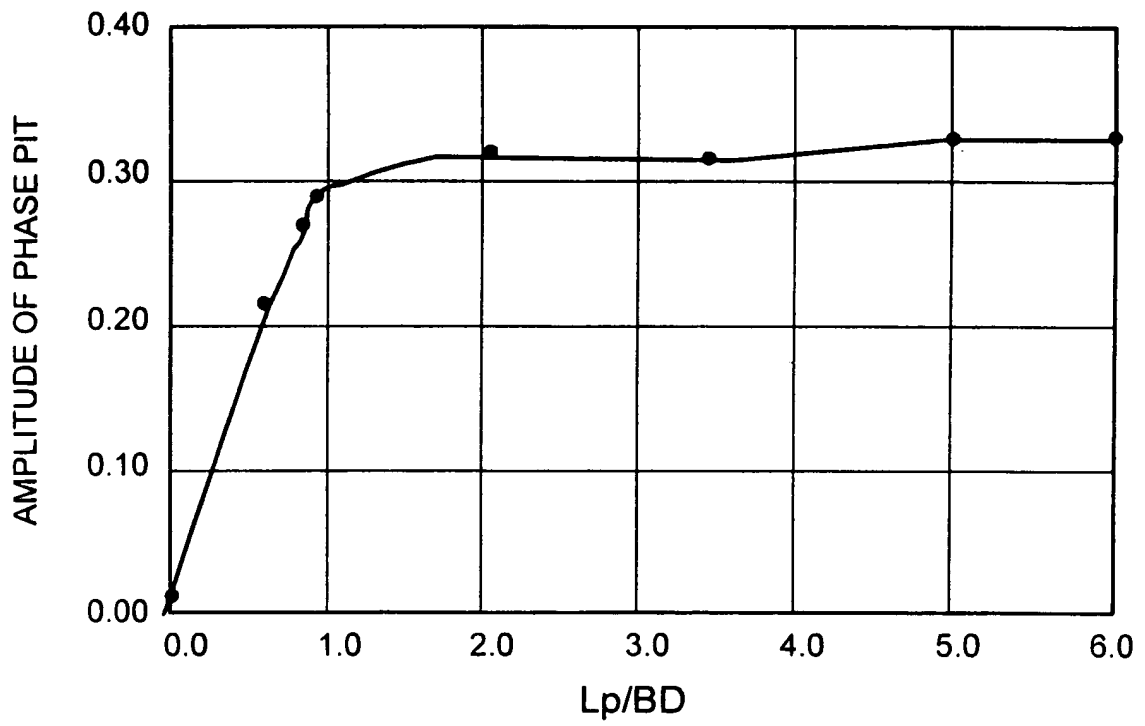


FIG. 5

FIG. 6A

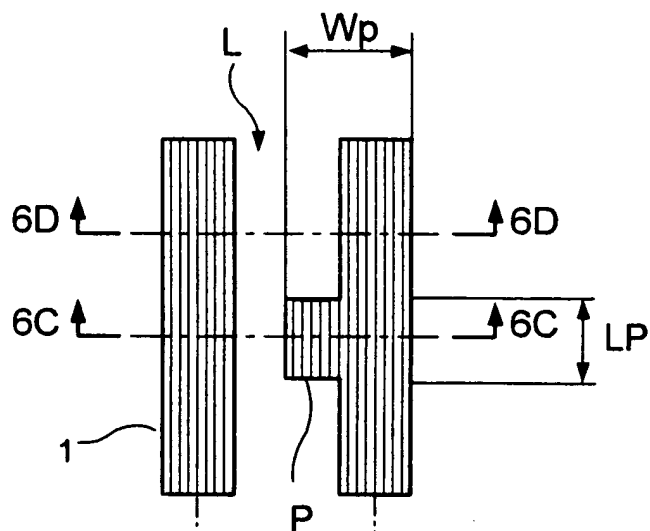


FIG. 6B

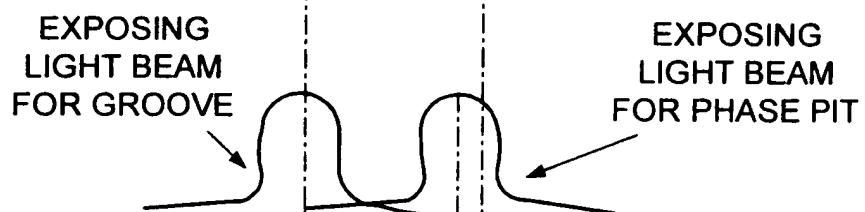


FIG. 6C

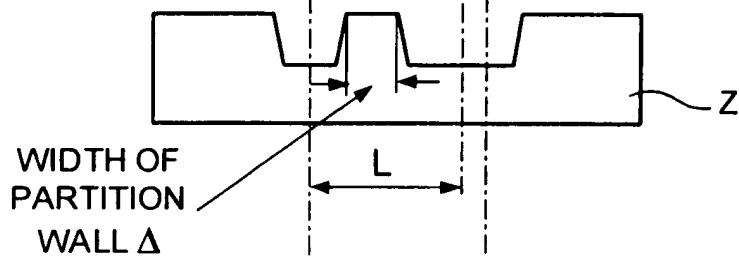
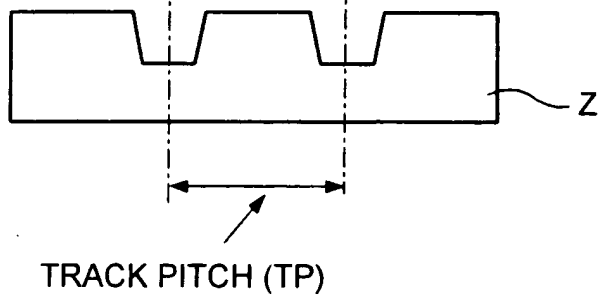


FIG. 6D



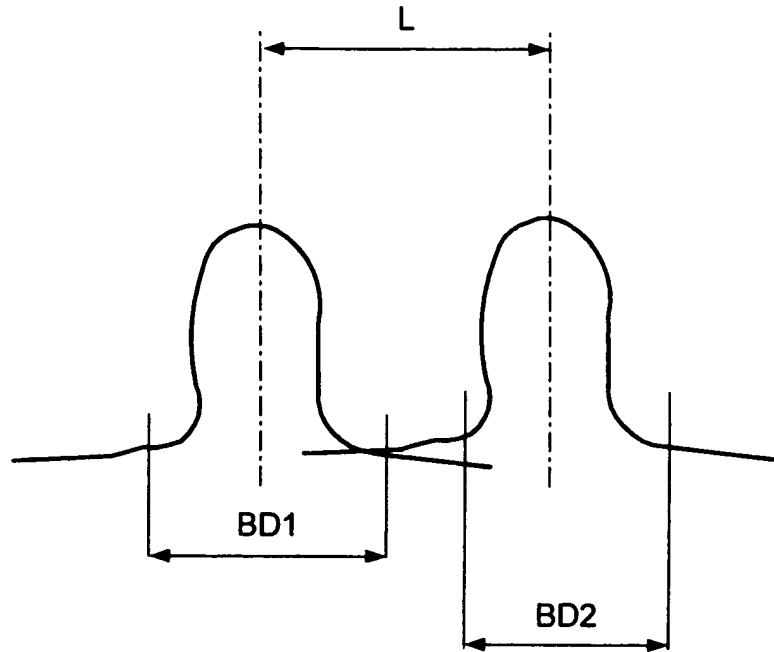


FIG. 7

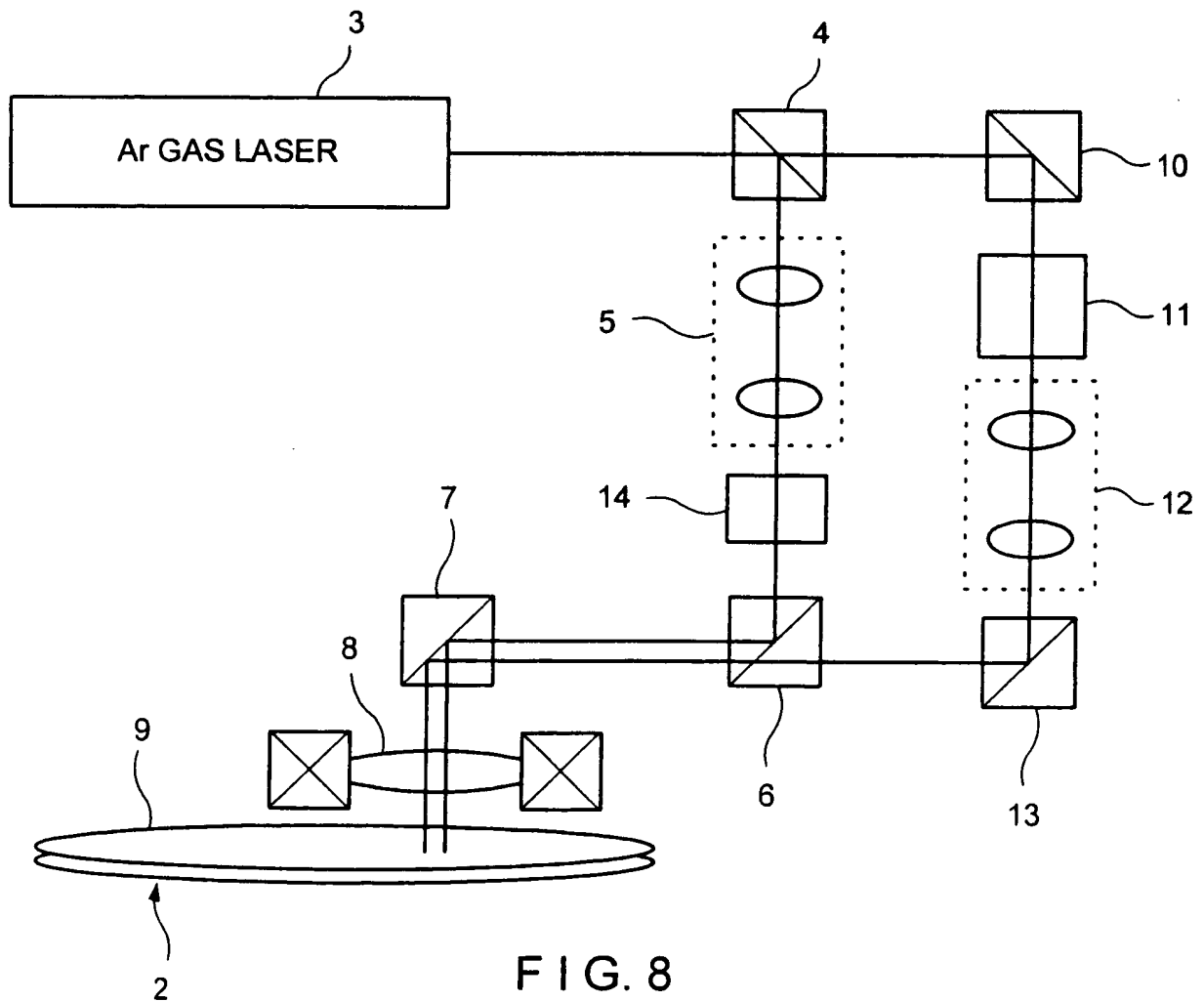


FIG. 8

FIG. 9A

MAKING OF RESIST  
ORIGINAL BOARD

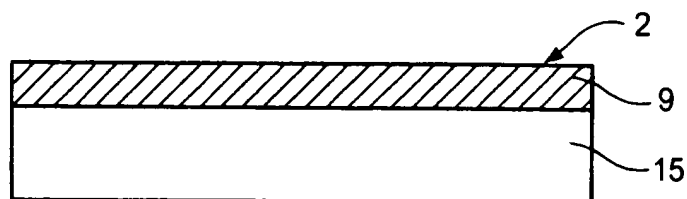


FIG. 9B

EXPOSING OF  
ORIGINAL BOARD

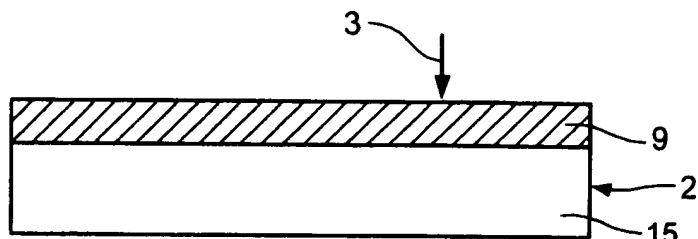


FIG. 9C

DEVELOPING

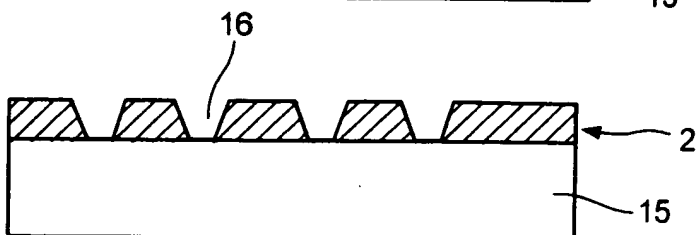


FIG. 9D

PROCESSING OF  
CONDUCTIVE FILM



FIG. 9E

NI ELECTROFORMING

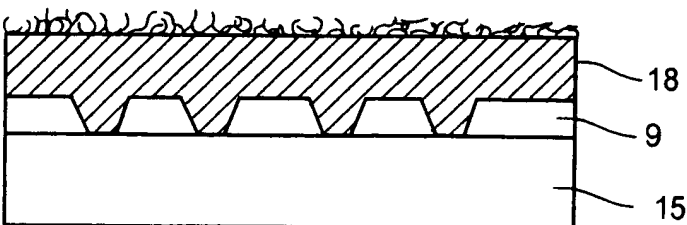
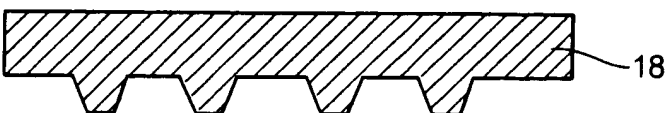


FIG. 9F

PEELING-OFF  
CLEANING  
POLISHING OF REAR SURFACE  
FINAL PROCESSING





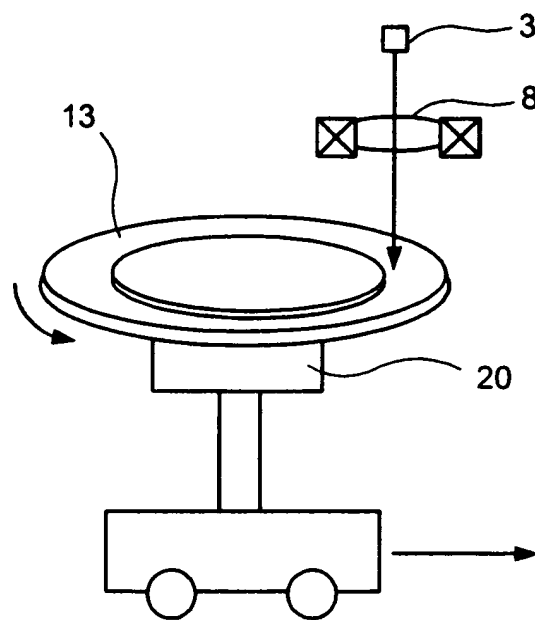


FIG. 10

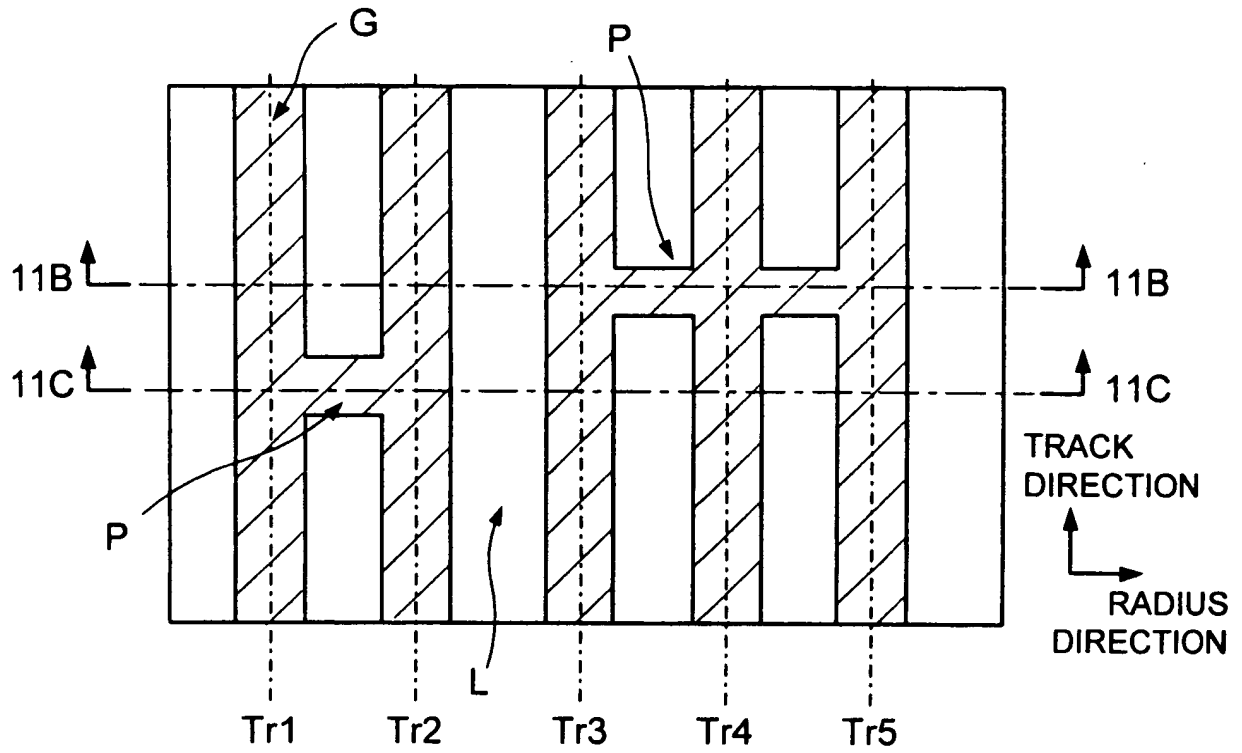


FIG. 11A  
PRIOR ART

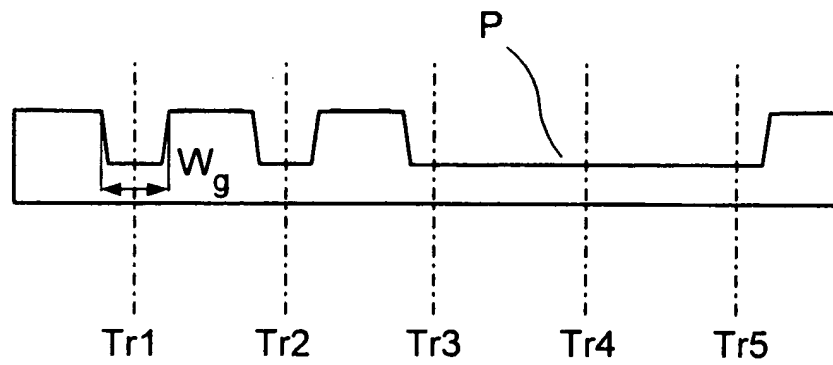


FIG. 11B  
PRIOR ART

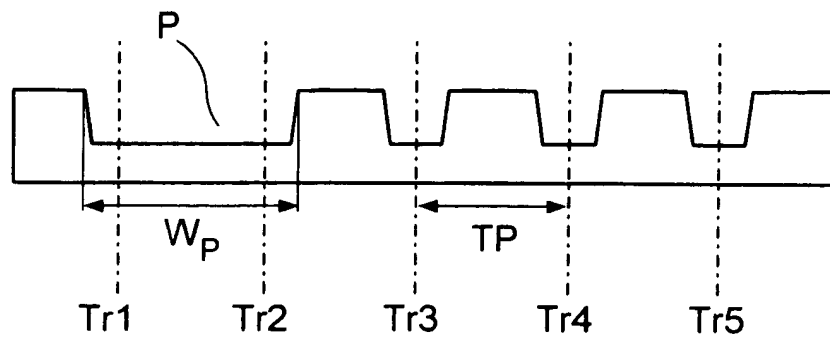


FIG. 11C  
PRIOR ART

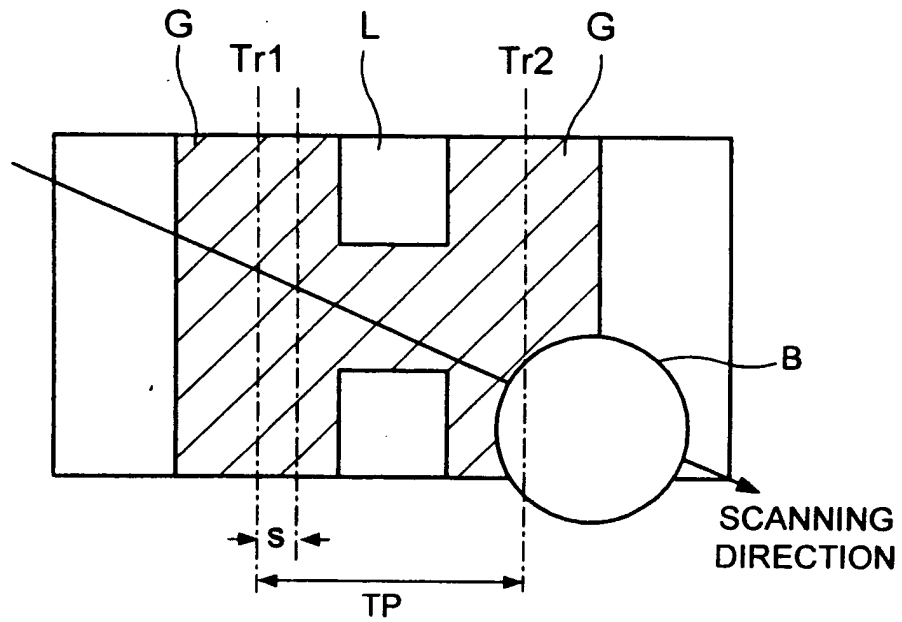


FIG. 12A

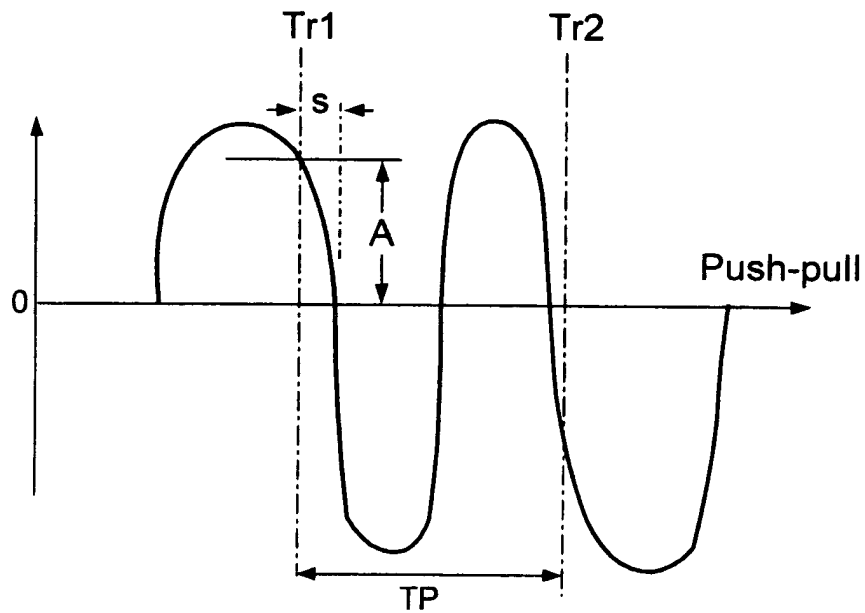


FIG. 12B

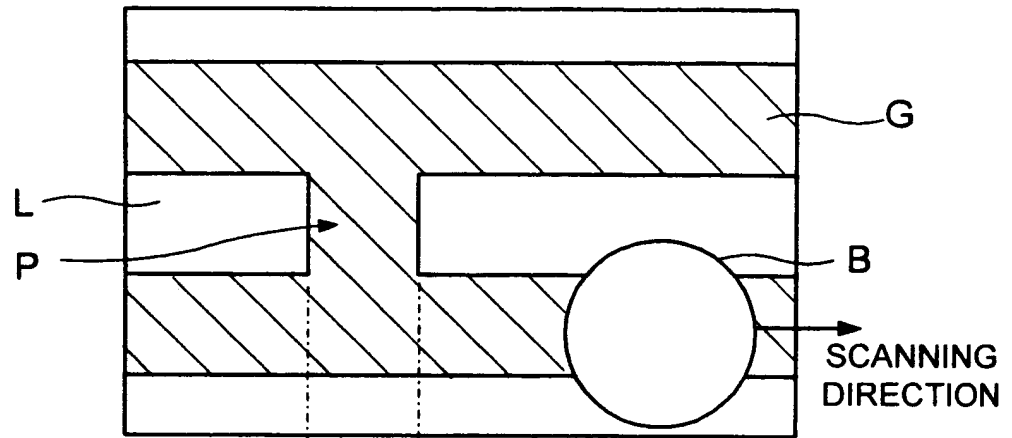


FIG. 13A

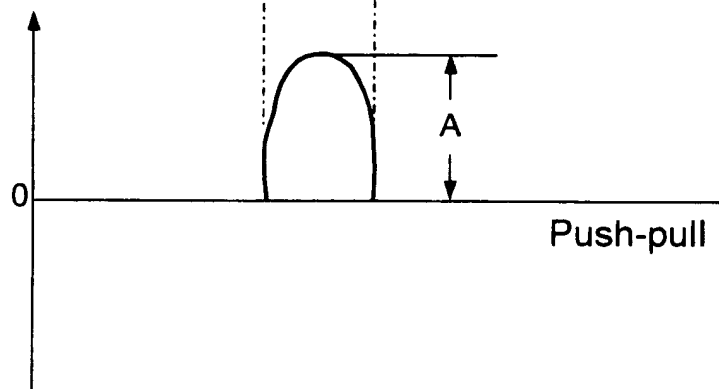


FIG. 13B

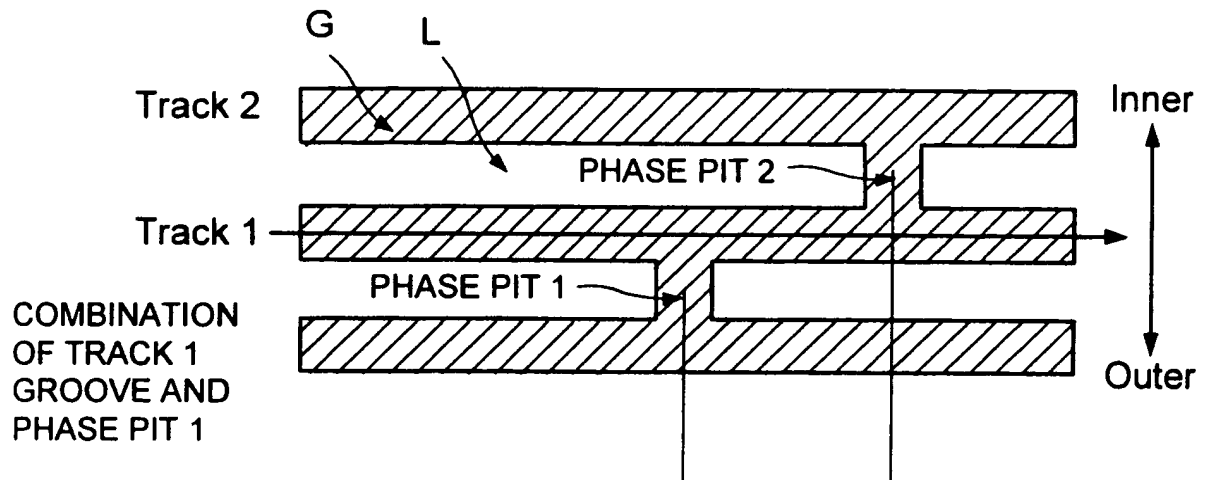


FIG. 14A

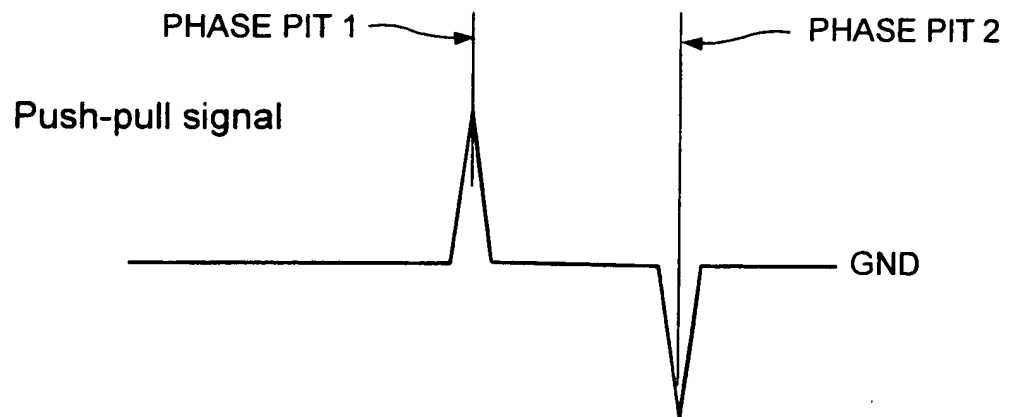


FIG. 14B

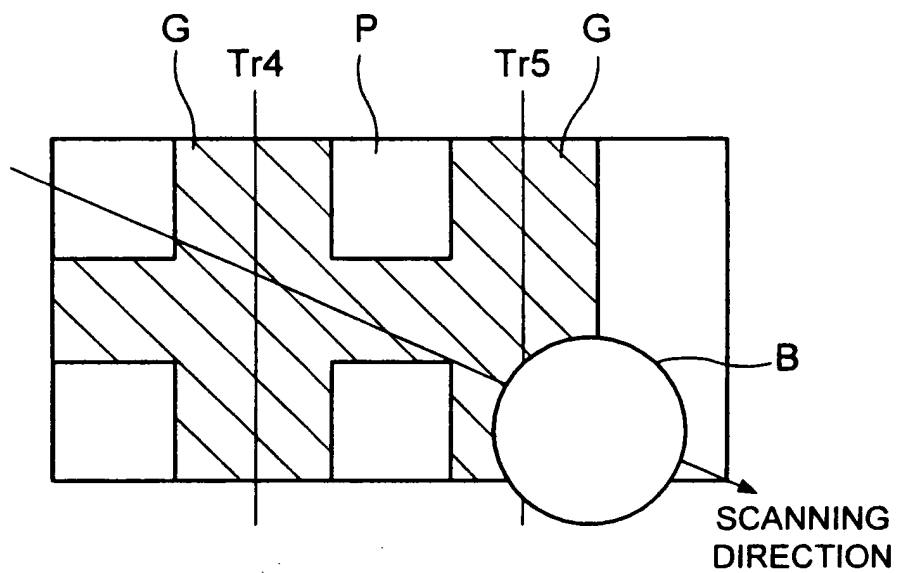


FIG. 15A

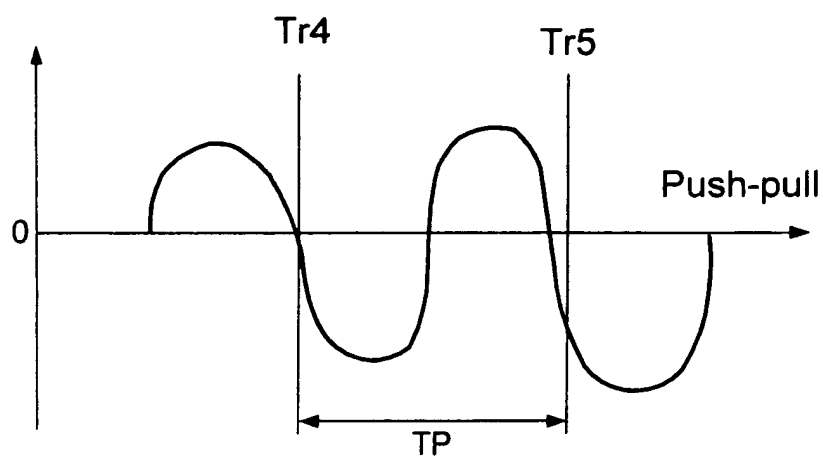
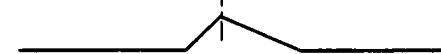
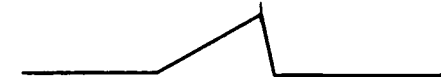
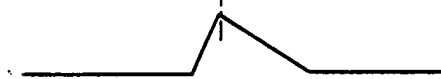


FIG. 15B

## Push-pull signal



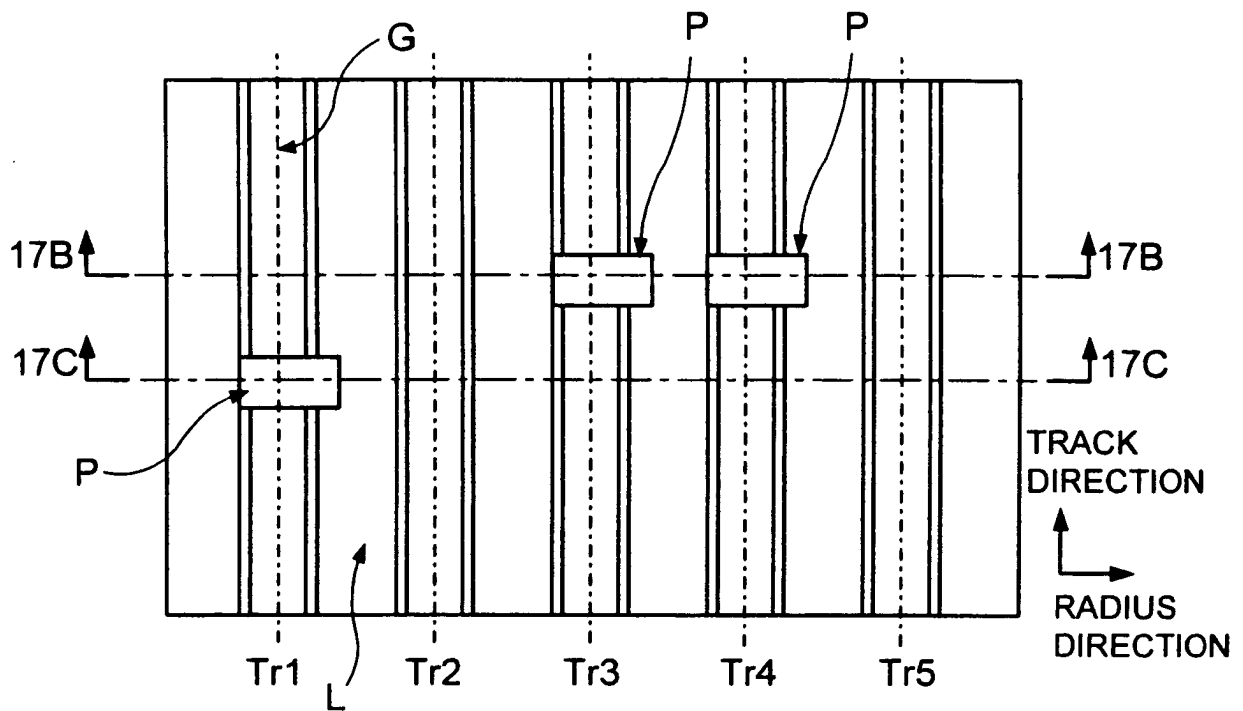


FIG. 17A  
PRIOR ART

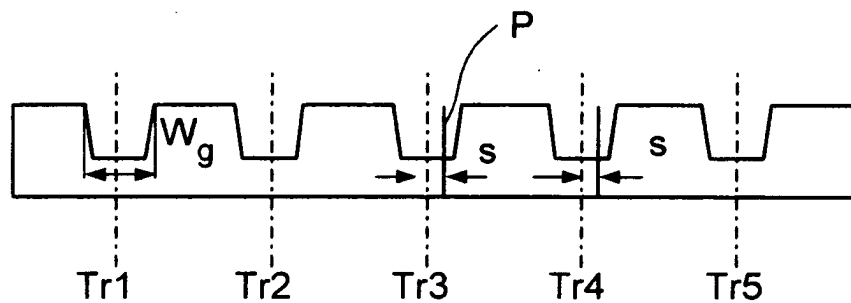


FIG. 17B  
PRIOR ART

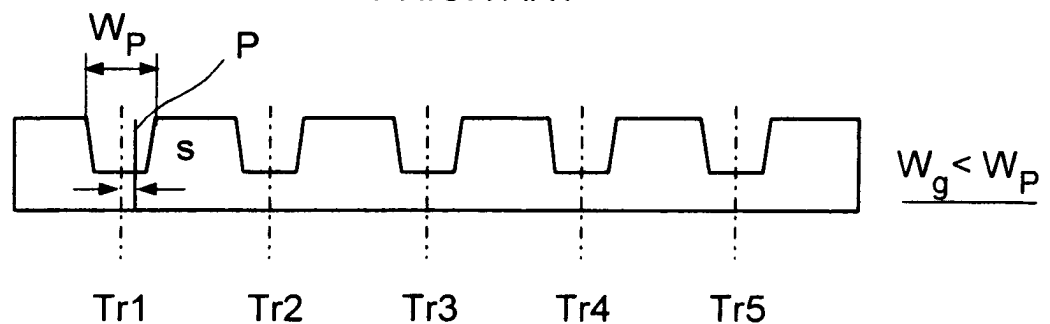


FIG. 17C  
PRIOR ART



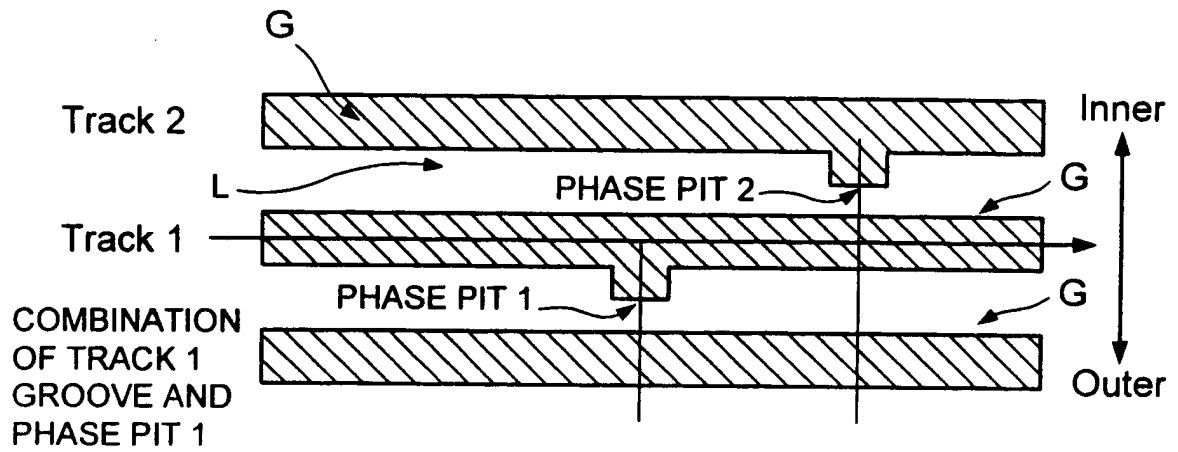


FIG. 18A  
PRIOR ART

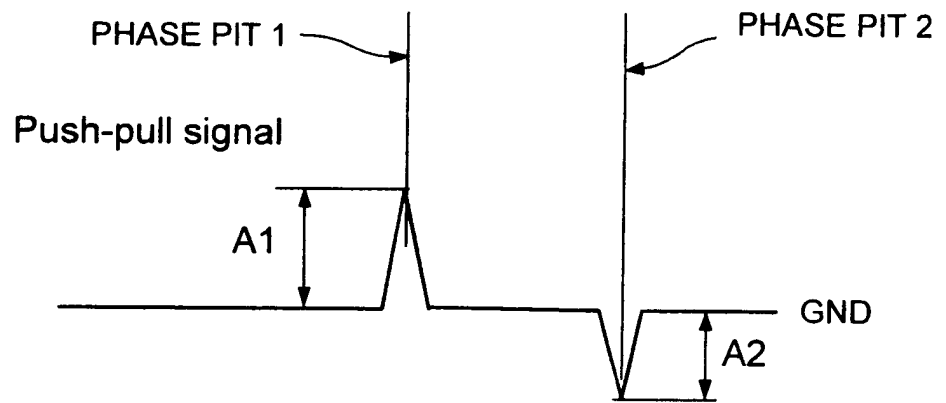


FIG. 18B  
PRIOR ART